

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
LIANG WANG	06/15/2017
RAJESH KATKAR	06/15/2017
RECEIVING PARTY DATA	
Name:	INVENSAS CORPORATION
Street Address:	3025 ORCHARD PARKWAY
City:	SAN JOSE
State/Country:	CALIFORNIA
Postal Code:	95134
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16712357
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	IN001-0221-US-03
NAME OF SUBMITTER:	CHRISTOPHER W. LATTIN
SIGNATURE:	/Christopher W. Lattin/
DATE SIGNED:	12/12/2019
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 2	
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source=IN001-0221-US-03_Parent-Assign-Decl-signed_2019-12-12#page2.tif	

COMBINED DECLARATION UNDER 37 CFR 1.63 AND ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, an ASSIGNOR named below,

Liang WANG of Milpitas, California, US
Rajesh KATKAR of Milpitas, California, US

hereby sell, assign and transfer to

ASSIGNEE: **INVENSAS CORPORATION**, a Delaware corporation having a place of business at 3025 Orchard Parkway, San Jose, CA 95134,

its successors, assigns and legal representatives, my entire right, title and interest throughout the world, including all rights to claim priority, in and to the invention(s) disclosed in:

- ☐ U.S. Patent Application executed on or about the date of this Assignment,
- ☐ U.S. Patent Application executed on _____, or
- ☒ U.S. Patent Application No.: 15/624,494, filed on June 15, 2017
- ☐ International Application No.: PCT/_____, filed on _____

ENTITLED: **MULTI-CHIP MODULES FORMED USING WAFER-LEVEL
PROCESSING OF A RECONSTITUTE WAFER**

and naming as

INVENTOR(S): **Liang WANG and Rajesh KATKAR**

including without limitation, my entire right, title and interest in and to any and all United States and foreign applications (including any and all provisional, international, regional and foreign national applications) for said invention(s), including non-provisionals, divisions, continuations, continuations-in-part, renewals, substitutes and extensions thereof, and in and to any and all patents of every country or region that may be granted or have been granted for said invention(s), including any reissues and reexaminations thereof.

Assignors hereby grant limited power of attorney to the attorneys/agents associated with Customer No. 79220 to update this document, as necessary, with an application number and a filing date for the above-referenced application.

OATH/DECLARATION

This Assignment may also serve as an oath or declaration in accord with 37 C.F.R. § 1.63(e) and, as such, as an inventor executing below, I do hereby state that I believe I am the original inventor or an original joint inventor of an invention claimed in any above-identified U.S. Patent Application or International Application designating the United States and do hereby state that such application is and was made or authorized to be made by me. I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

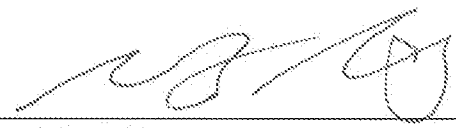
I authorize ASSIGNEE to apply for patents of foreign countries for said invention(s), and to claim all rights of priority without further authorization from me.

I agree to execute any and all papers useful in connection with any and all U.S. and foreign applications (including international, regional, and foreign national applications), and generally to do everything possible to aid ASSIGNEE, its successors, assigns and nominees, at their request and reasonable expense, in obtaining and enforcing patents for said invention(s) in all countries.

I hereby covenant that no assignment, sale, license, agreement, or encumbrance has been or will be made or entered into that would conflict with this Assignment.

I authorize and request the Commissioner of Patents and Trademarks to issue any U.S. Letters Patent that may be granted for said invention(s) to ASSIGNEE, its successors or assigns.

Executed on 06/15/2017
Date

by 
Liang Wang

Executed on 6/15/2017
Date

by 
Rajesh Katkar